EAST Search History

EAST Search History (Prior Art)

Ref#	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	548	"438"/\$.ccls. and solder same flux and flux with clean\$	US-PGPUB; USPAT	OR	ON	2009/07/31 09:49
L2	123	"438"/\$.ccls. and solder same flux and flux with clean\$ and inject\$	US-PGPUB; USPAT	OR	ON	2009/07/31 09:49
L3	24	"438"/\$.ccls. and solder same flux and flux with clean\$ and inject\$ same encapsulat \$	US-PGPUB; USPAT	OR	ON	2009/07/31 09:49
L4	1	"6849955".pn.	US-PGPUB; USPAT	OR	ON	2009/07/31 10:40
S1	561273	pad	US-PGPUB; USPAT	OR	ON	2009/07/29 14:35
S2	25772	pad and reflow\$4	US-PGPUB; USPAT	OR	ON	2009/07/29 14:37
S3	1633585	pad and reflow\$4 (underfill\$ fill\$4)	US-PGPUB; USPAT	OR	ON	2009/07/29 14:40
S4	16675	pad and reflow\$4 and (underfill\$ fill\$4)	US-PGPUB; USPAT	OR	ON	2009/07/29 14:40
S5	4248	pad and reflow\$4 and (underfill\$ fill\$4) and flux	US-PGPUB; USPAT	OR	ON	2009/07/29 14:40
S6	3539	pad and reflow\$4 and (underfill\$ fill\$4) and flux same solder\$4	US-PGPUB; USPAT	OR	ON	2009/07/29 14:41
S7	1088	pad and reflow\$4 and (underfill\$ fill\$4) and flux same solder\$4 and dic\$4	US-PGPUB; USPAT	OR	ON	2009/07/29 14:45
S8	932	pad and reflow\$4 and (underfill\$ fill\$4) and flux same solder\$4 and dic\$4 and bump	US-PGPUB; USPAT	OR	ON	2009/07/29 14:46
S9	187	pad and reflow\$4 and (underfill\$ fill\$4) same encapsulat\$4 and flux same solder\$4 and dic \$4 and bump	US-PGPUB; USPAT	OR	ON	2009/07/29 14:59

S10	33	("4610079" "4670088" "5143865"	US-PGPUB;	OR	OFF	2009/07/30
310		"4670098" "5143865" "5496775" "554887" "5703406" "5824569" "5834843" "5844779" "589317" "5933713" "5950070" "6054772" "6077380" "6097098" "6107164" "6137164" "6150717" "6150748" "6181569" "6297553" "6331450" "6331450"	USPAT; USOCR	Un	51	10:51
		"6379999" "6499216").PN. OR ("6900079").URPN.	***************************************	***************************************	***************************************	
S11	4	"6821878".pn. "6338985".pn. "6506681".pn. "6774497".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/30 12:40
S12	2	("20030230801" "6569710").PN. OR ("7282391").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/30 12:53
Si3	26	("3401126" "3429040" "3915780" "4904644" "4966857" "5447886" "5491111" "5836765" "5612513" "5866943" "5869353" "5020219" "6087202" "61001081 "6316289").PN. OR ("6569710").URPN.	US-PGPUB; USPAT; USOOR	OR	OFF	2009/07/30 12:55
S14	343	dic\$4 with wafer same array and dic\$4 with substrate same sing\$8	US-PGPUB; USPAT; USOCR	OR	ON	2009/07/30 13:08
S15	343	dic\$4 with wafer same array and dic\$4 with substrate same sing\$7	US-PGPUB; USPAT; USOCR	OR	ON	2009/07/30 13:08
S16	90	dic\$4 with wafer with array and dic\$4 with substrate with sing\$7	US-PGPUB; USPAT; USOOR	OR	ON	2009/07/30 13:09

S17	128	dic\$4 with wafer same array and dic\$4 with substrate same sing\$7 and (bond\$4 attach\$4) with array with substrate	US-PGPUB; USPAT; USOCR	OR	ON	2009/07/30 13:23
S18	54	dic\$4 with wafer with array and dic\$4 with substrate same sing\$7 and (bond\$4 attach\$4) with array with substrate	US-PGPUB; USPAT; USOCR	OR	ON	2009/07/30 13:27
S19	1	10/581395	US-PGPUB; USPAT; USOCR	OR	ON	2009/07/30 13:58
\$20	124	("5258330" "5627405" "5627405" "5627405" "5759873" "5767010" "5786270" "5786270" "5817541" "5831832" "5834830" "5844304" "5858815" "5862816" "5862812" "5872051" "587709" "5883392" "589332" "589332" "5892290" "5892293" "5892290" "5892290" "5892290" "5892290" "5892290" "589744").PN. OR ("6181569").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/30
S21	1	"6181569".pn. and pad	US-PGPUB; USPAT; USOCR	OR	ON	2009/07/30 16:13
S22	187	pad and reflow\$4 and (underfill\$ fill\$4) same encapsulat\$4 and flux same solder\$4 and dic \$4 and bump	US-PGPUB; USPAT	OR	ON	2009/07/30 16:21
S23	24	pad and reflow\$4 and (underfill\$ fill\$4) same encapsulat\$4 and flux same dip\$3 same solder \$4 and dic\$4 and bump	US-PGPUB; USPAT	OR	ON	2009/07/30 17:16
S24	25	pad and reflow\$4 and (underfill\$ fill\$4) same encapsulat\$4 and flux same dip\$4 same solder \$4 and dic\$4 and bump		OR	ON	2009/07/30 17:16

\$25	23	pad and reflow\$4 and	US-PGPUB:	OB	ON	2009/07/30
OE3	20			OIT	OIV	
		(underfill\$ fill\$4) same	USPAT			17:38
		encapsulat\$4 and flux				
	•	same dip\$4 same solder				
		\$4 and dic\$4 and bump				
		and flux same clean\$				

7/31/2009 10:55:38 AM

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